

# Self-Oscillating Half-Bridge Driver

#### **Features**

- Floating channel designed for bootstrap operation
- Integrated 600 V half-bridge gate driver
- 15.6 V zener clamp on Vcc
- True micropower start up
- Tighter initial dead time control
- Low temperature coefficient dead time
- Shutdown feature (1/6th Vcc) on CT pin
- Increased undervoltage lockout Hysteresis (1 V)
- Lower power level-shifting circuit
- Constant LO, HO pulse widths at startup
- Lower di/dt gate driver for better noise immunity
- Low side output in phase with RT
- Excellent latch immunity on all inputs and outputs
- ESD protection on all leads

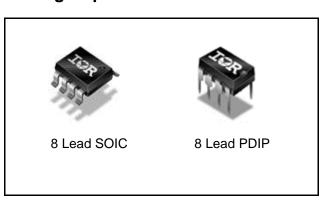
### **Product Summary**

Voffset	600 V max.
Duty Cycle	50%
T <sub>r</sub> / T <sub>f</sub>	80 ns / 40 ns
$V_{CLAMP}$	15.6 V
Dead time (typ.)	1.2 μs
lo+/lo- (typ.)	180 mA / 260 mA

# Description

The IR25603(S) incorporates a high voltage half-bridge gate driver with a front end oscillator similar to the industry standard CMOS 555 timer. A shutdown feature has been designed into the CT pin, so that both gate driver outputs can be disabled using a low voltage control signal. In addition, the gate driver output pulse widths are the same once the rising undervoltage lockout threshold on Vcc has been reached, resulting in a more stable profile of frequency vs time at startup. Special attention has been paid to maximizing the latch immunity of the device and providing comprehensive ESD protection on all pins.

### **Package Options**

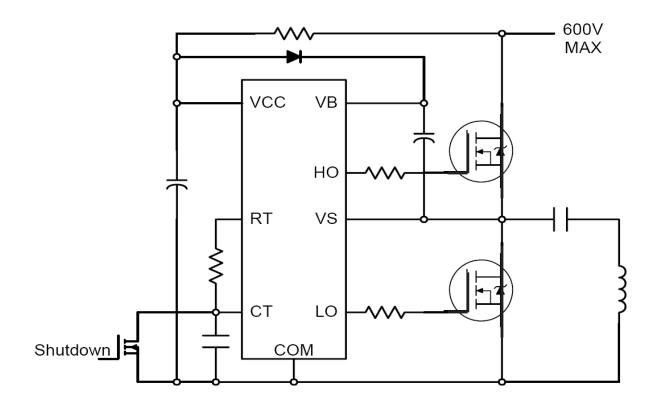


## **Ordering Information**

Danie Bard Namel an	Package Type	Package Type Standard		On level to Deat News to a	
Base Part Number	r ackage Type	Form	Quantity	Orderable Part Number	
IR25603SPBF	SO8N	Tube	95	IR25603SPBF	
IR25603SPBF	SO8N	Tape and Reel	2500	IR25603STRPBF	
IR25603PBF	PDIP8	Tube	50	IR25603PBF	



# **Typical Connection Diagram**





#### **Absolute Maximum Ratings**

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units	
V <sub>B</sub>	High side floating absolute voltage		-0.3	625	
Vs	High side floating supply offset voltage	9	V <sub>B</sub> - 25	V <sub>B</sub> + 0.3	
V <sub>HO</sub>	High side floating output voltage		V <sub>S</sub> - 0.3	V <sub>B</sub> + 0.3	
$V_{LO}$	Low side output voltage		-0.3	V <sub>CC</sub> + 0.3	7 v
V <sub>RT</sub>	R <sub>T</sub> pin voltage		-0.3	V <sub>CC</sub> + 0.3	
V <sub>CT</sub>	C <sub>T</sub> pin voltage		-0.3	V <sub>CC</sub> + 0.3	
Icc	Supply current†		_	25	A
I <sub>RT</sub>	R <sub>T</sub> pin current		-5	5	mA mA
dVs/dt	Allowable offset supply voltage transic	ent	_	50	V/ns
D-	Package power dissipation @ TA ≤	8 lead PDIP	_	1	W
$P_{D}$	+25°C	8 lead SOIC	_	0.625	VV
D4h	Thermal resistance, junction to	8 lead PDIP	_	125	°C/W
$Rth_JA$	ambient	8 lead SOIC	_	200	C/VV
TJ	Junction temperature		_	150	
T <sub>S</sub>	Storage temperature		-55	150	°C
TL	Lead temperature (soldering, 10 second	nds)	_	300	

## **Recommended Operating Conditions**

For proper operation the device should be used within the recommended conditions. The  $V_S$  offset rating is tested with all supplies biased at 15V differential.

Symbol	Definition	Min.	Max.	Units
V <sub>B</sub>	High side floating supply absolute voltage	V <sub>CC</sub> – 0.7	$V_{CLAMP}$	
Vs	Steady state high side floating supply offset voltage	††	600	V
Vcc	Supply voltage	10	$V_{CLAMP}$	
Icc	Supply current	+++	5	mA
T <sub>A</sub>	Ambient temperature	-40	125	°C

 $<sup>\</sup>dagger$  This IC contains a zener clamp structure between the chip  $V_{CC}$  and COM which has a nominal breakdown voltage of 15.6V. Please note that this supply pin should not be driven by a DC, low impedance power source greater than the  $V_{CLAMP}$  specified in the Electrical Characteristics section.

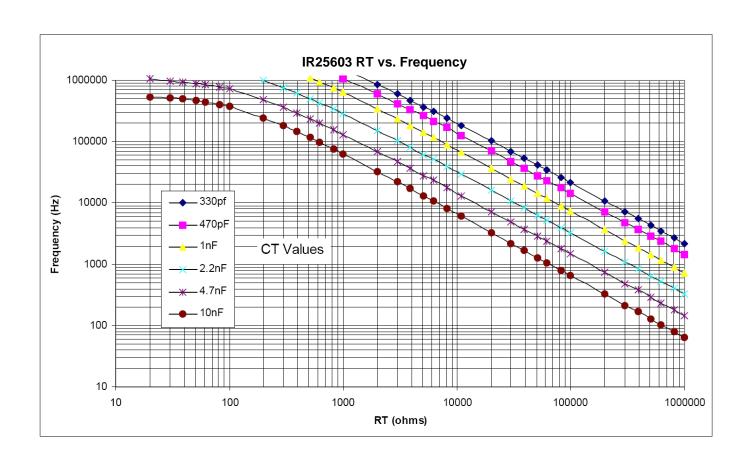
<sup>††</sup> Care should be taken to avoid output switching conditions where the VS node flies inductively below ground by more than 5V.

<sup>†††</sup> Enough current should be supplied to the V<sub>CC</sub> pin of the IC to keep the internal 15.6V zener diode clamping the voltage at this pin.



# **Recommended Component Values**

Symbol	Component	Min.	Max.	Units
R <sub>T</sub>	Timing resistor value	10	_	kΩ
Ст	C <sub>T</sub> pin capacitor value	330	_	pF





### **Electrical Characteristics**

 $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 12V, CL = 1000 pF, CT = 1nF and  $T_A$  = 25°C unless otherwise specified.

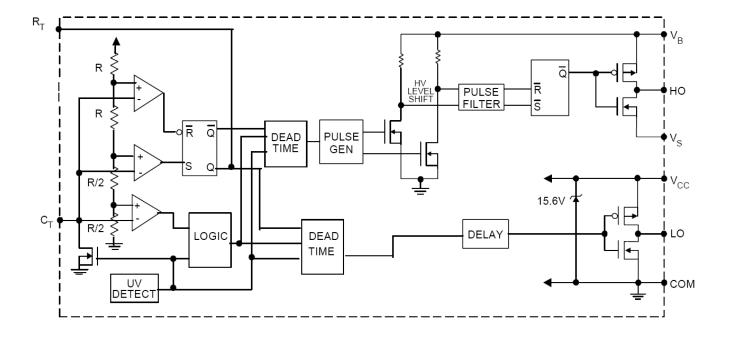
Low Voltage Supply Characteristics						
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
V <sub>CCUV+</sub>	V <sub>CC</sub> supply undervoltage positive going threshold	8.1	9.0	9.9		
V <sub>CCUV</sub> -	V <sub>CC</sub> supply undervoltage negative going threshold	7.2	8.0	8.8	V	
V <sub>CCUVH</sub>	V <sub>CC</sub> undervoltage hysteresis	0.5	1.0	1.5	1	
I <sub>QCCUV</sub>	Micropower startup V <sub>CC</sub> supply current	_	75	150	μA	V <sub>CC</sub> ≤ V <sub>CCUV</sub> -
IQCC	Quiescent V <sub>CC</sub> supply current	_	500	950	] '	
V <sub>CLAMP</sub>	V <sub>CC</sub> zener clamp voltage	14.4	15.6	16.8	V	$I_{CC} = 5mA$
Floating Su	upply Characteristics					
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
I <sub>QBSUV</sub>	Micropower startup V <sub>BS</sub> supply current	_	0	10	μA	V <sub>CC</sub> ≤ V <sub>CCUV</sub> -
I <sub>QBS</sub>	Quiescent V <sub>BS</sub> supply current	_	30	50	Ī .	
V <sub>BSMIN</sub>	Minimum required V <sub>BS</sub> voltage for proper functionality from R <sub>T</sub> to HO	_	4.0	5.0	V	$V_{CC} = V_{CCUV+} + 0.1V$
I <sub>LK</sub>	Offset supply leakage current	_	_	50	μA	$V_{B} = V_{S} = 600V$
Oscillator I	/O Characteristics  Definition	Min.	Тур.	Max.	Units	Test Conditions
- Cyllidei		19.4	20	20.6	O mico	$R_T = 36.9k\Omega$
fosc	Oscillator frequency	94	100	106	kHz	$R_T = 7.43k\Omega$
d	R <sub>T</sub> pin duty cycle	48	50	52	%	f <sub>O</sub> < 100kHz
I <sub>CT</sub>	C <sub>T</sub> pin current	_	0.001	1.0	μA	
I <sub>CTUV</sub>	UV-mode C <sub>T</sub> pin pull down current	0.3	0.7	1.2	mA	$V_{CC} = 7V$
V <sub>CT+</sub>	Upper C <sub>T</sub> ramp voltage threshold		8			
$V_{CT-}$	Lower C <sub>T</sub> ramp voltage threshold	_	4	_	V	
$V_{CTSD}$	C <sub>T</sub> voltage shutdown threshold	1.8	2.1	2.4		
		_	10	50		I <sub>RT</sub> = 100 μA
V <sub>RT+</sub>	High-level $R_T$ output voltage, $V_{CC}$ - $V_{RT}$	_	100	300		I <sub>RT</sub> = 1mA
			10	50		I <sub>RT</sub> = 100 μA
V <sub>RT</sub> -	Low-level R <sub>T</sub> output voltage	_	100	300	mV	I <sub>RT</sub> = 1mA
$V_{RTUV}$	UV-mode R <sub>T</sub> output voltage		0	100		V <sub>CC</sub> ≤ V <sub>CCUV</sub> -
\/	SD-Mode R <sub>T</sub> output voltage, V <sub>CC</sub> -	_	10	50		$I_{RT} = 100 \mu A,$ $V_{CT} = 0V$
V <sub>RTSD</sub>	V <sub>RT</sub>	_	10	300		I <sub>RT</sub> = 1mA, V <sub>CT</sub> = 0V



# **Electrical Characteristics (cont.)**

Gate Drive	Gate Driver Output Characteristics					
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
VOH	High level output voltage, V <sub>BIAS</sub> -V <sub>O</sub>	_	0	100		I <sub>O</sub> = 0A
VOL	Low-level output voltage, V <sub>O</sub>	_	0	100	mV	$I_O = 0A$
VOL_UV	UV-mode output voltage, V <sub>O</sub>	_	0	100		$I_{O} = 0A$ $V_{CC} \le V_{CCUV}$
t <sub>r</sub>	Output rise time	_	80	150		
t <sub>f</sub>	Output fall time	_	45	100	ns	
t <sub>sd</sub>	Shutdown propagation delay	_	660	_	] [	
t <sub>d</sub>	Output dead time (HO or LO)	0.75	1.20	1.65	μS	
I <sub>O+</sub>	Output source current	_	180	_	m A	
I <sub>O-</sub>	Output sink current	_	260	_	mA	

# **Functional Block Diagram**

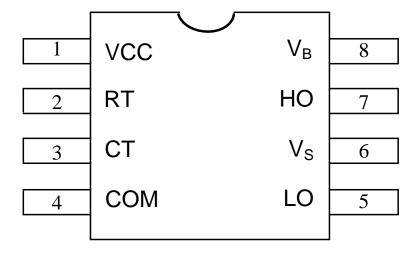




# **Lead Definitions**

Symbol	Description
Vcc	Logic and internal gate drive supply voltage
R <sub>T</sub>	Oscillator timing resistor input
Ст	Oscillator timing capacitor input
COM	IC power and signal ground
LO	Low side gate driver output
Vs	High voltage floating supply return
НО	High side gate driver output
V <sub>B</sub>	High side gate driver floating supply

# **Lead Assignments**





### **Application Information and Additional Details**

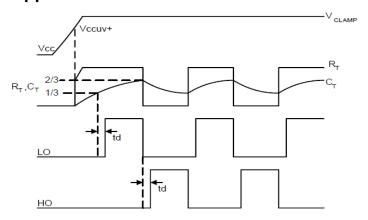


Figure 1. Input/Output Timing Diagram

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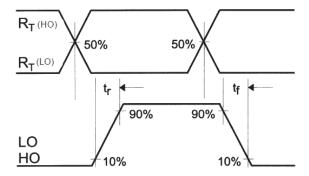


Figure 2. Switching Time Waveform Definitions

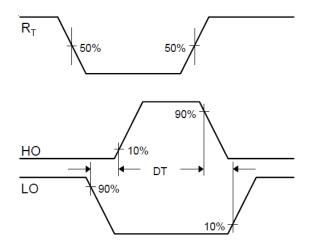
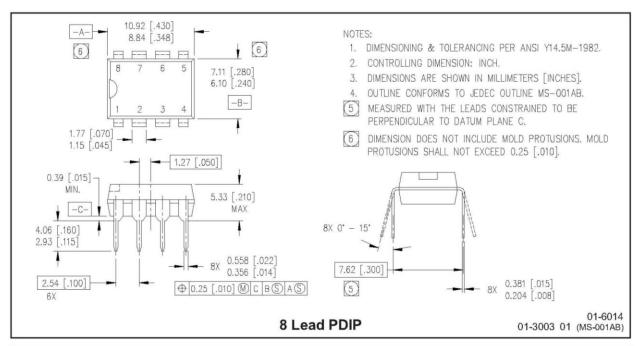


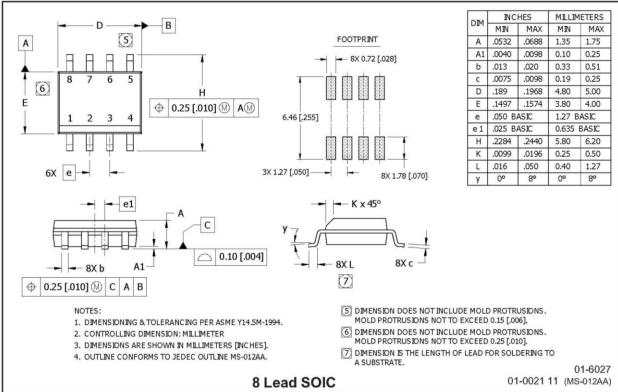
Figure 3. Deadtime Waveform Definitions

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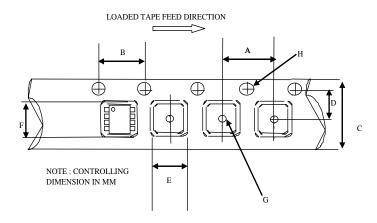
#### **Package Details**





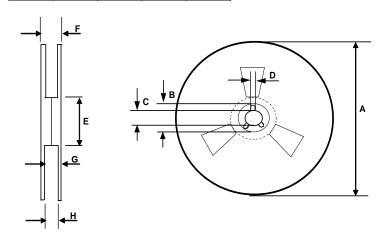


# Tape and Reel Details, SO8N



#### CARRIER TAPE DIMENSION FOR 8SOICN

	Metric		Imp	erial
Code	Min	Max	Min	Max
A	7.90	8.10	0.311	0.318
В	3.90	4.10	0.153	0.161
С	11.70	12.30	0.46	0.484
D	5.45	5.55	0.214	0.218
E	6.30	6.50	0.248	0.255
F	5.10	5.30	0.200	0.208
G	1.50	n/a	0.059	n/a
Н	1.50	1.60	0.059	0.062

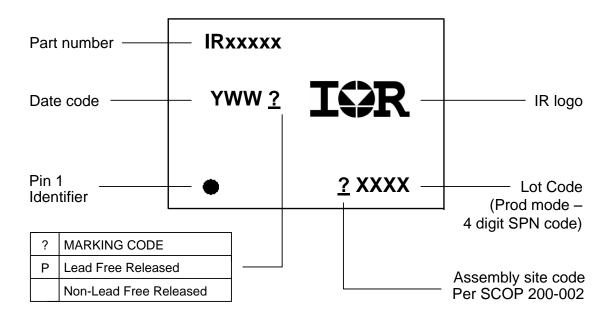


#### REEL DIMENSIONS FOR 8SOICN

	Metric		Imp	erial
Code	Min	Max	Min	Max
Α	329.60	330.25	12.976	13.001
В	20.95	21.45	0.824	0.844
B C	12.80	13.20	0.503	0.519
D	1.95	2.45	0.767	0.096
E	98.00	102.00	3.858	4.015
F	n/a	18.40	n/a	0.724
G	14.50	17.10	0.570	0.673
Н	12.40	14.40	0.488	0.566



# **Part Marking Information**





## **Qualification Information**<sup>†</sup>

-, -, -, -, -, -, -, -, -, -, -, -, -, -	
	Industrial <sup>††</sup> (per JEDEC JESD 47)
Qualification Level	Comments: This family of ICs has passed JEDEC's Industrial qualification. IR's Consumer qualification level is
	granted by extension of the higher Industrial level.
Moisture Sensitivity Level	SOIC8N MSL2 <sup>†††</sup> (per IPC/JEDEC J-STD 020)
moisture deficiently Level	PDIP8 Not applicable (non-surface mount package style)
RoHS Compliant	Yes

- † Qualification standards can be found at International Rectifier's web site <a href="http://www.irf.com/">http://www.irf.com/</a>
- †† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information.
- ††† Higher MSL ratings may be available for the specific package types listed here. Please contact your International Rectifier sales representative for further information.

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233 Kansas St., El Segundo, California 90245 Tel: (310) 252-7105